



QLSP1306A  
0603 0.6mm height  
Amber LED



## Product Outline:

This is the much smaller than lead frame type components, 0603 package, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.

## Features:

- Compatible with automatic placement equipment.
- RoHS compliant
- Compatible with infrared and vapor phase reflow solder process.
- Custom Bin available upon special request
- View angle typ. 120°
- **0.6mm** Height

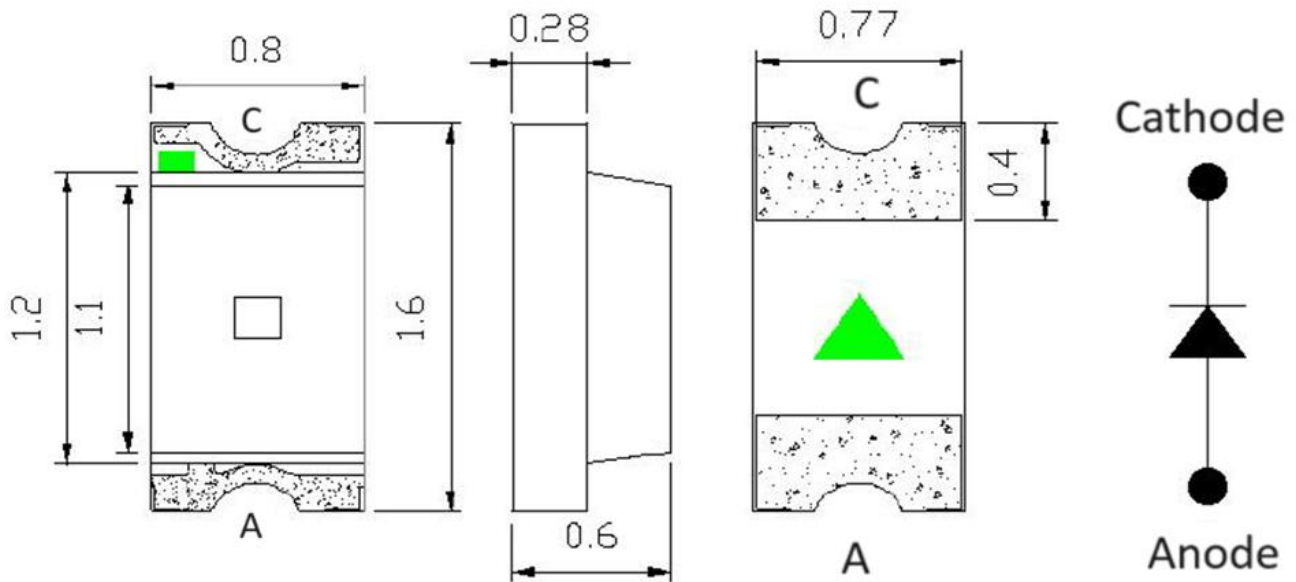
## Application:

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

## Compliance and Certification:

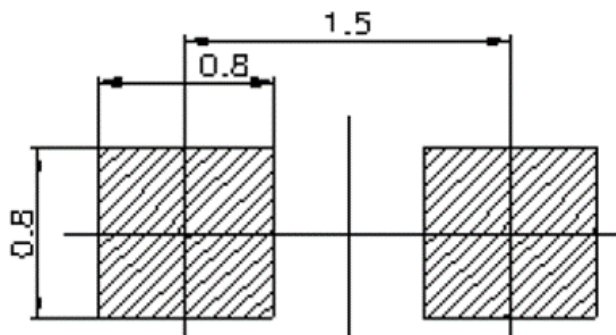


## Mechanical Property: (Dimension)



- \* All dimensions are in millimeters,
- \* Tolerances are  $\pm 0.10\text{mm}$ .

## Recommended Solder footprint:



- \* All dimensions are in millimeters.
- \* Reflow soldering must not be performed more than twice.



# Characteristics

## ■ Absolute Maximum Ratings

(Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	$V_R$	5	V
DC Forward Current	$I_f$	25	mA
Pulse Forward Current (Duty 1/10 @1KHz)	$I_{FP}$	60	mA
Total Power Dissipation	$P_d$	55	mW
Electrostatic Discharge (HBM)	ESD	150	V
Storage Temperature	$T_{stg}$	-40 ~ 85	°C
Operation Temperature	$T_{opr}$	-40 ~ 85	°C
Soldering Temperature	$T_{sol}$	260 < 10 sec	°C

(1) Proper current rating must be observed to maintain junction temperature below maximum at all time

## ■ Electrical / Optical Characteristic

(Ta=25 oC)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	$I_v$	71.5		285	mcd	If=20mA
Peak Wavelength	$\lambda_p$		608		nm	
Dominant Wavelength	$\lambda_d$	600		610	nm	
Forward Voltage	$V_f$	1.9		2.3	V	
View Angle	$\theta$		120		deg	

- (1). Tolerance of Luminous Intensity:  $\pm 11\%$
- (2). Tolerance of Dominant Wavelength  $\pm 1\text{nm}$
- (3). Tolerance of measurement:  $V_F = \pm 0.1\text{V}$



## ■ Groups

### Forward Voltage (V<sub>F</sub>) Bin:

VF Rank (V)				Condition
Color	Code name	Low	High	unit
Amber	Q	1.9	2.0	IF=20mA
	R	2.0	2.1	
	S	2.1	2.2	
	T	2.2	2.3	

### Dominant Wavelength Bin:

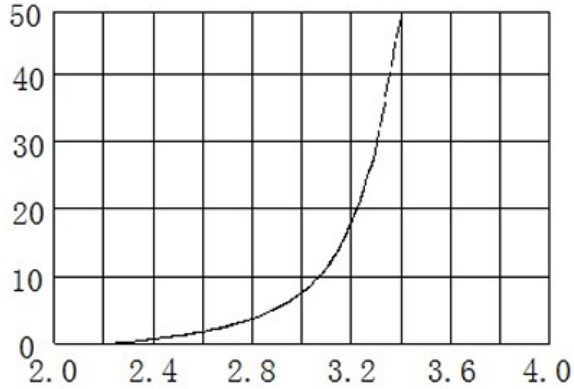
Rank (nm)				Condition
Color	Code name	Low	High	Unit
Amber				IF=20mA
	A4	600	605	
	A5	605	610	

### Brightness Bin:

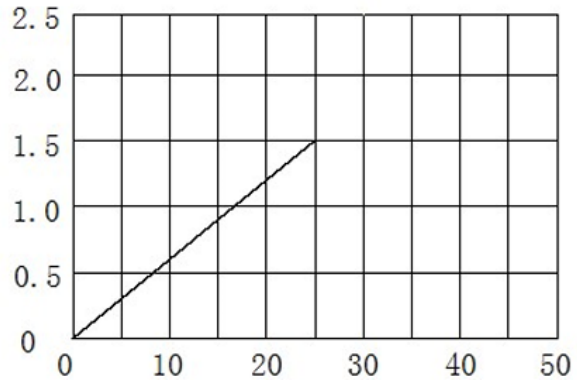
Rank (mcd)				Condition
Color	Code name	Low	High	Unit
Amber	Q	71.5	112.5	IF=20mA
	R	112.5	180	
	S	180	285	



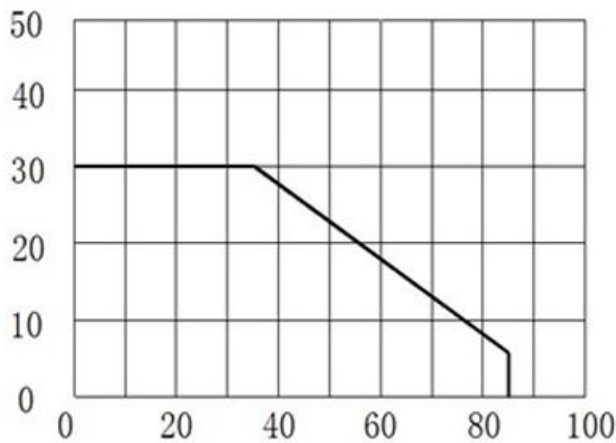
## Characteristic Curves



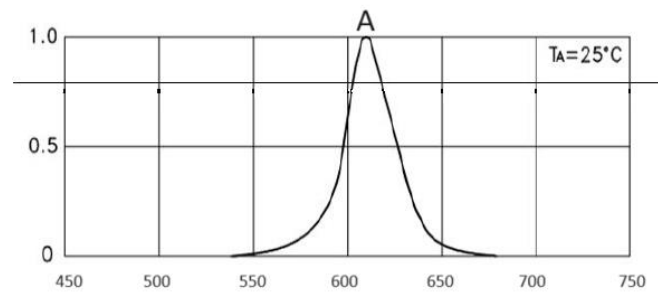
Forward current vs forward voltage



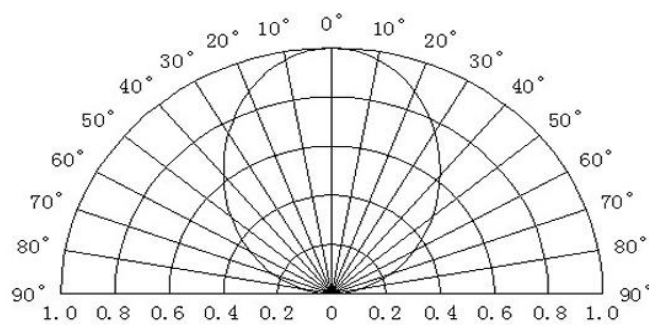
Relative luminous intensity vs forward current



Forward current vs Temp



Spectrum Distribution



Radiation pattern



### ■ Reliability test:

No	Item	Condition	Time/Cycle	Sample size
1	Steady State Operating Life of Room Temperature	25°C Operating	1000 Hrs	20 pcs
2	Steady State Operating Life of Low Temperature -40°C	-40°C Operating	1000 Hrs	20 pcs
3	Steady State Operating Life of Low Temperature 60°C	60°C Operating	1000 Hrs	20 pcs
4	Steady State Operating Life of Low Temperature 85°C	85°C Operating	1000 Hrs	20 pcs
5	Low temperature storage -40°C	-40°C Storage	1000 Hrs	20 pcs
6	High temperature storage 100°C	100°C Storage	1000 Hrs	20 pcs
7	Steady State Operating Life of High Humidity Heat 60°C 90%	60°C/90% Operating	1000 Hrs	20 pcs
8	Steady State Pulse Operating Life Condition	25°C 10Hz duty=1/10 Operating	200 Cycle	20 pcs
9	Resistance to soldering heat on PCB (JEDEC MSL3)	pre-store@60°C, 60%RH for 52hrs Tslid max.=260 10sec	3 Times	20 pcs
10	Heat Cycle Test (JEDEC MRC)	25°C~65°C~-10°C, 90%RH, 24hr/1cycle	10 Cycle	20 pcs
11	Thermal shock	-40°C/ 20min~ 5min~100°C /20min	300 Cycle	20 pcs

### ■ Judgment Criteria:

Item	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	R : IF=20 mA	$\Delta Vf < 10\%$
Luminous Flux	Iv		$\Delta Iv < 30\%$

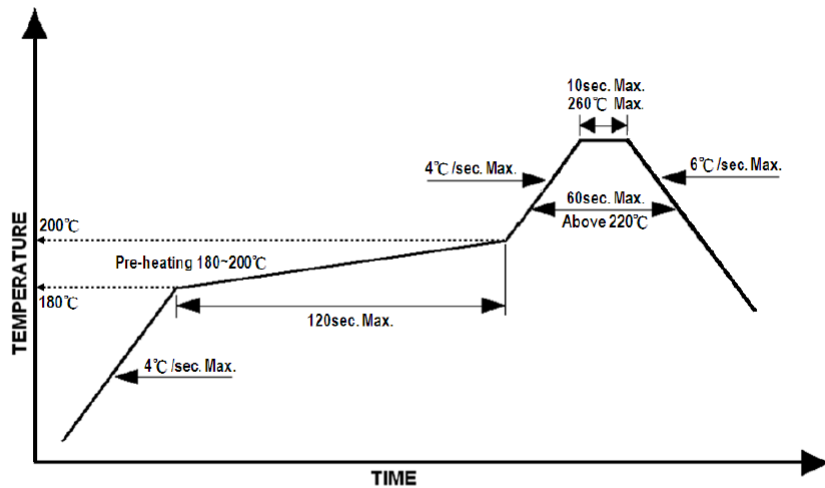


## Solder Profile:

-The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

1. Operating temp.: Above 220 °C ,60 sec.
2. Peak temp.:260 °C Max.,10sec Max.
3. Reflow soldering should not be done more than two times.
4. Never attempt next process until the component is cooled down to room temperature after reflow.
5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

### Lead-free Solder Profile



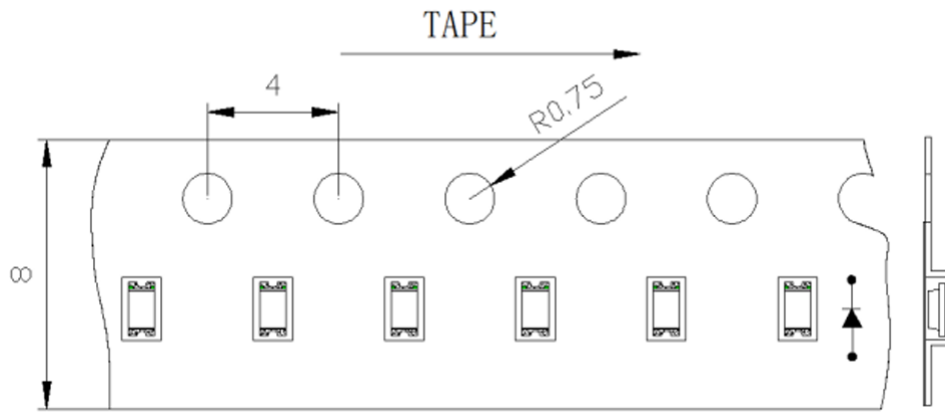
### Reworking

- Rework should be completed within 5 seconds under 260°C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

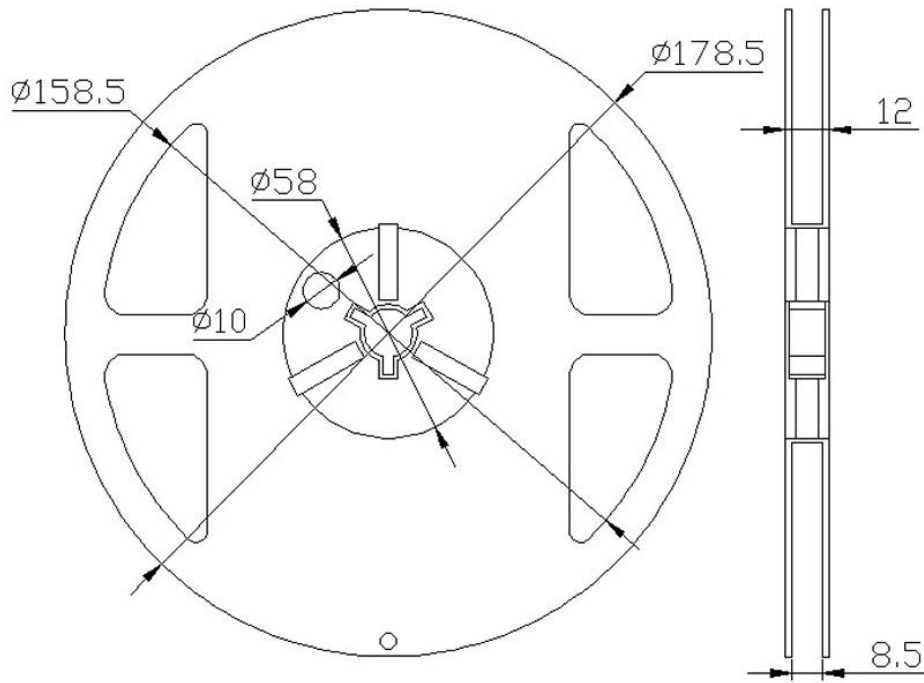


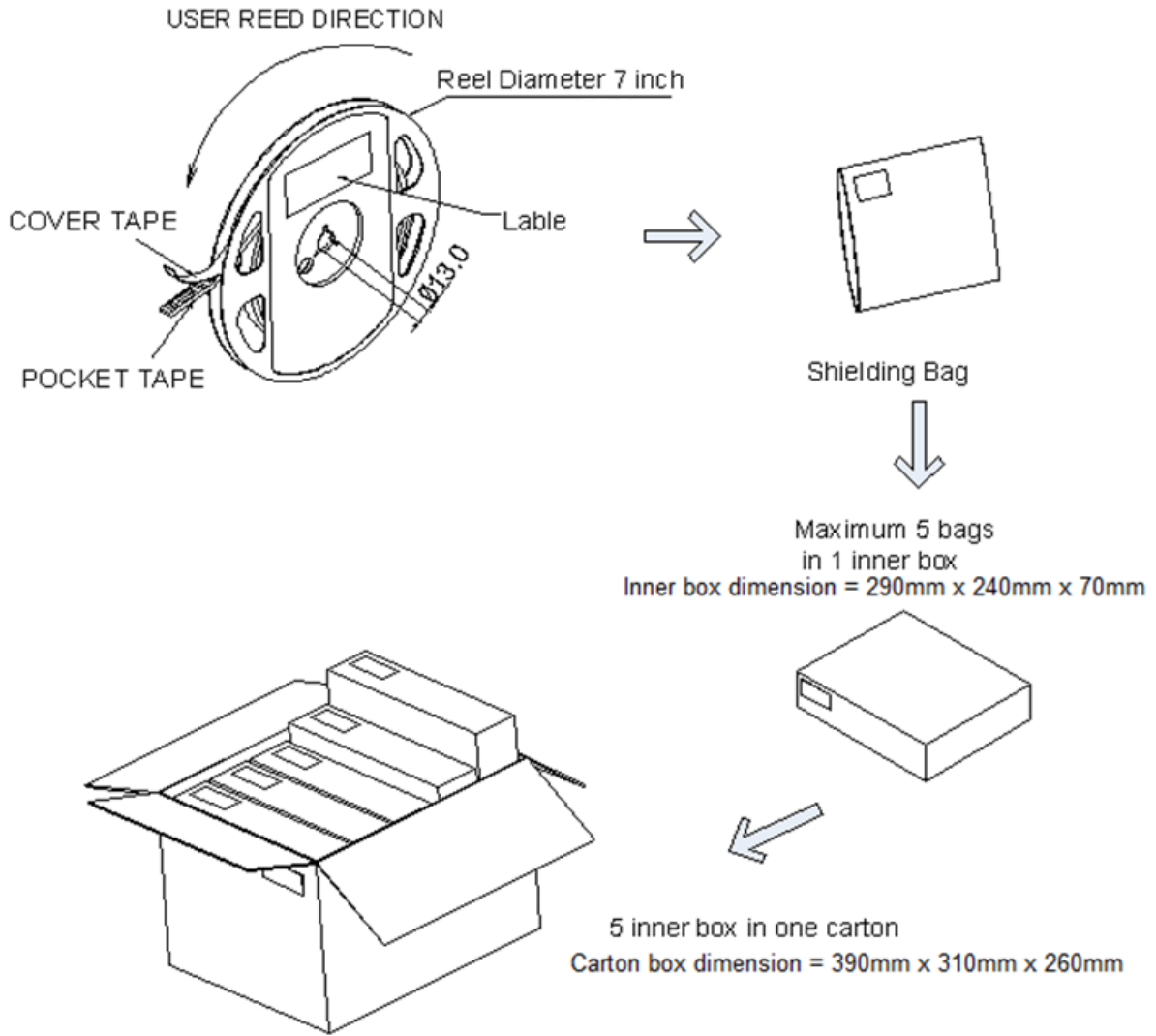


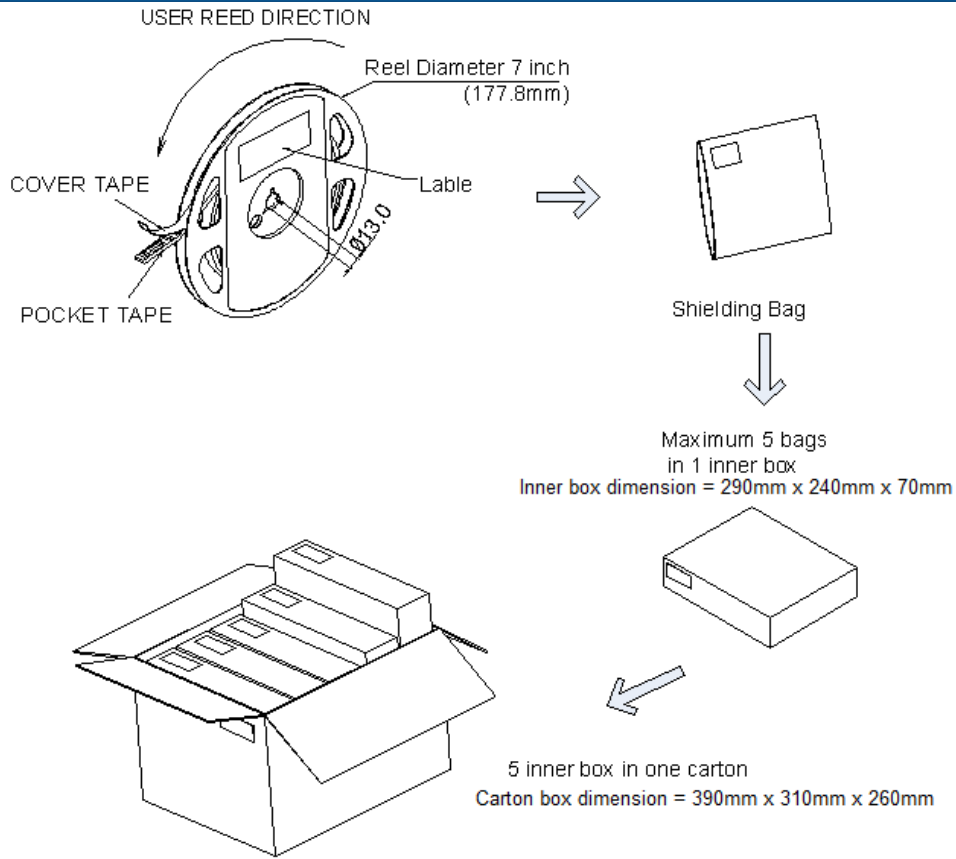
## Taping & Packing:



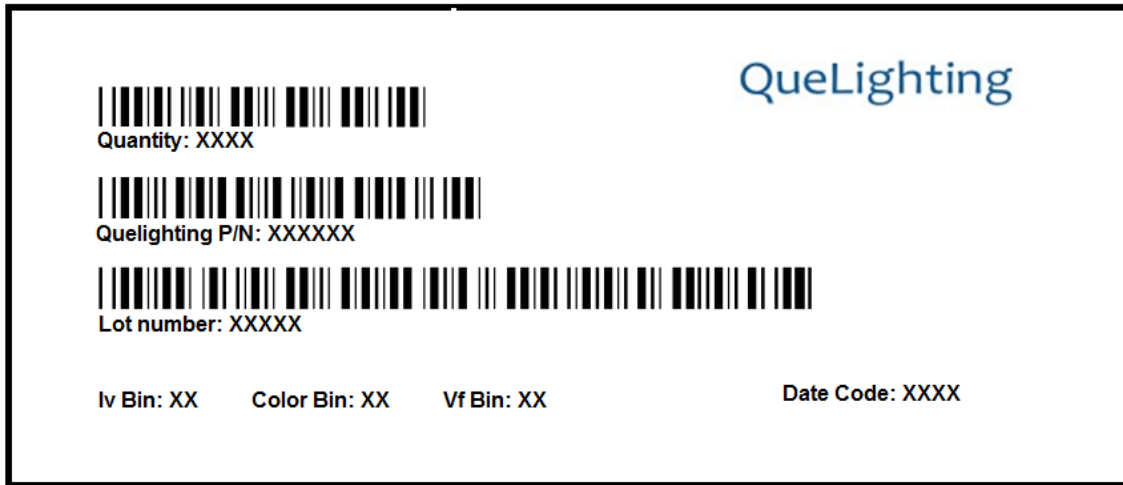
Unit : mm







## Labeling



### Ordering Information:

Part #	Multiple Quantities	Quantity per Reel
QLSP1306A		4000 pcs



## Revision History:

Revision Date:	Changes:	Version #:
03-13-2023	Initial release	1.0

